

*S. Stevenson*  
*# 2*  
*10-3-01*

PATENT

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Group Art Unit: Unknown

Inventor: Yu, et al

Serial No. To Be Assigned

Filed: Herewith

For: Thermal Compensation Method For Forming Semiconductor  
Integrated Circuit Microelectronic Fabrication

Attorney Docket No.: 67,200-506



DISCLOSURE STATEMENT  
UNDER 37 C.F.R. § 1.56

Assistant Commissioner  
for Patents  
Washington, D.C. 20231

Sir:

In compliance with 37 C.F.R. § 1.56, the art listed and identified on the attached Form PTO-1449 is being submitted herewith for consideration by the Examiner. A copy of each of the listed references is included herewith.

It is Applicant's opinion that the claims presently on file patentably distinguish the present invention from each of these references. The above references are being cited only in the interests of candor and without any admission that they constitute

. ' U.S.S.N.: Filed Herewith

statutory prior art or contain matter which anticipates the invention or which would render the same obvious, either singly or in combination, to a person of ordinary skill in the art.

Respectfully submitted,

TUNG & ASSOCIATES



By

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